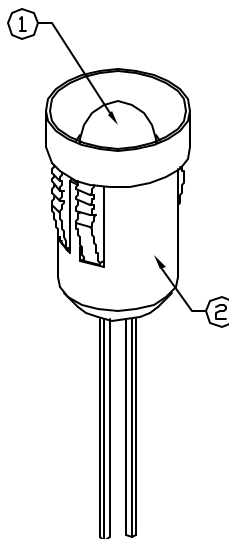
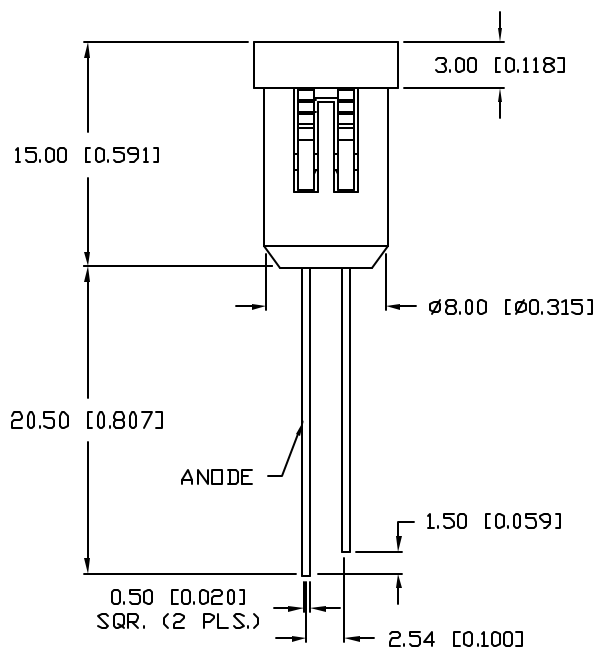
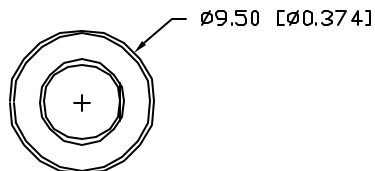


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PART NUMBER
SSI-LXR5020YD

REV.
B

REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE
A	E.C.N. #10BRDR. & REDRAWN.	6.10.99
B	E.C.N. #10BRDR. & REDRAWN.	8.14.01



PANEL CUTOUT: 8.05mm.
PANEL THICKNESS: 0.6-2.6mm

ELECTRO-OPTICAL CHARACTERISTICS $T_A=25^{\circ}\text{C}$ $I_f=20\text{mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		585		nm	
FORWARD VOLTAGE		2.1	2.5	V_f	
REVERSE VOLTAGE	5.0			V_r	$I_f=100\mu\text{A}$
AXIAL INTENSITY		30		med	$I_f=20\text{mA}$
VIEWING ANGLE		60		2x theta	
EMITTED COLOR:	YELLOW				
EPOXY LENS FINISH:	YELLOW DIFFUSED				

LIMITS OF SAFE OPERATION AT 25°C

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	150	mA
STEADY CURRENT	30	mA
POWER DISSIPATION	105	mW
DERATE FROM 25°C	-1.2	mW/ $^{\circ}\text{C}$
OPERATING, STORAGE TEMP.	-40 TO +85	$^{\circ}\text{C}$
SOLDERING TEMP.	+260	$^{\circ}\text{C}$
2.0mm FROM BODY		3 SEC. MAX

* $t < 10\mu\text{s}$

NOTES:

- SSL-LX5093YD LED.
- SSH-RTF5020 HOLDER.

CAUTION: PRESSURE SENSITIVE ASSEMBLY
AVOID APPLYING PRESSURE TO LED
DURING PANEL ASSEMBLY.

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*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), X.X=±0.5 (±0.020), X.XX=±0.25 (±0.010), X.XXX=±0.127 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030). MIN= ^{+0.00} _{-0.00} DECIMAL PRECISION MAX.= ^{+0.00} _{-0.00} DECIMAL PRECISION

REV.
B

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T-5mm (T-1 3/4) ROUND LED PANEL INDICATOR,
585nm YELLOW LED, YELLOW DIFFUSED LENS.

RELIABILITY NOTE
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY: GT	CHECKED BY:	APPROVED BY:	DATE: 8.26.96
			PAGE: 1 OF 1
			SCALE: N/A